



## Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-02-27
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty statement**

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**Legal statement**

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32U535CEU6	71MI*455XXXY	A	998Z	2024-02-27
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	113	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFN	7x7	48	Flat	
Comment	Package : A0B9 UFQFPN 7X7X0.55 48L 0.5 MM PITCH 8202210			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-23rd January 2024				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	0			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	71M1*455XXX		113.4270		7000000.0	1000000.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	4.072	mg	supplier	die	Silicon (Si)	7440-21-3		3.674	mg	902163	32387
				supplier	metallization	Aluminium (Al)	7429-90-5		0.045	mg	10985	394
				supplier	metallization	Copper (Cu)	7440-50-8		0.131	mg	32269	1158
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.022	mg	5493	197
				supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	1373	49
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	343	12
				supplier	Passivation	Silicon Nitride	12033-89-5		0.031	mg	7552	271
				supplier	Passivation	Silicon Oxide	7631-86-9		0.162	mg	39821	1430
				supplier	Organic Compounds	Acrylic resin	Proprietary		0.041	mg	70000	366
				supplier	Organic Compounds	Polybutadiene derivative	Proprietary		0.012	mg	20000	104
Glue epoxy (EN4900GC)	M-011 Other inorganic materials	0.593	mg	supplier	Organic Compounds	Butadiene copolymer	Proprietary		0.009	mg	15000	78
				supplier	Organic Compounds	Acrylate	Proprietary		0.032	mg	54000	282
				supplier	Organic Compounds	Epoxy resin	Proprietary		0.018	mg	30000	157
				supplier	Organic Compounds	Peroxide	Proprietary		0.005	mg	8000	42
				supplier	Organic Compounds	Additive	Proprietary		0.011	mg	18000	94
				supplier	Metals	Silver (Ag)	7440-22-4		0.465	mg	785000	4101
				supplier	Organic Compounds	Epoxy Resin A	Proprietary		0.736	mg	21000	6487
				supplier	Organic Compounds	Epoxy Resin B	Proprietary		0.736	mg	21000	6487
				supplier	Organic Compounds	Phenol Resin A	Proprietary		0.736	mg	21000	6487
				supplier	Glass	Silica(Amorphous)A	60676-86-0		27.347	mg	780450	241098
Mold Compound (EME-G770)	M-011 Other inorganic materials	35.040	mg	supplier	Glass	Silica(Amorphous)B	7631-86-9		4.041	mg	115320	35625
				supplier	Organic Compounds	Carbon Black	1333-86-4		0.218	mg	6230	1925
				supplier	Metallic compounds	Metal Hydroxide	Proprietary		0.491	mg	14000	4325
				supplier	Organic Compounds	Phenol Resin B	Proprietary		0.736	mg	21000	6487
				supplier	Metals	Gold (Au)	7440-57-5		1.044	mg	1000000	9204
				supplier	Metals	Tin (Sn)	7440-31-5		1.078	mg	1000000	9507
				supplier	Metals	Copper (Cu)	7440-50-8		55.120	mg	917140	485952
				supplier	Metals	Nickel (Ni)	7440-02-0		1.352	mg	22500	11922
				supplier	Metals	Silicon (Si)	7440-21-3		0.156	mg	2600	1378
				supplier	Metals	Magnesium (Mg)	7439-95-4		0.069	mg	1150	609
Bonding Wire (Au)	Bonding Wire	1.044	mg	supplier	Metals	Silver (Ag)	7440-22-4		3.402	mg	56610	29995
				supplier	Metals	Tin (Sn)	7440-31-5		11.499	mg	999900	101377
				supplier	Metals	Impurities	Proprietary		0.001	mg	100	10
Plating (Sn)	M-011 Other inorganic materials	1.078	mg	supplier	Metals	Gold (Au)	7440-57-5		1.044	mg	1000000	9204
				supplier	Metals	Tin (Sn)	7440-31-5		1.078	mg	1000000	9507
Leadframe (C7025 + Ag)	Copper & its alloys	60.100	mg	supplier	Metals	Copper (Cu)	7440-50-8		55.120	mg	917140	485952
				supplier	Metals	Nickel (Ni)	7440-02-0		1.352	mg	22500	11922
				supplier	Metals	Silicon (Si)	7440-21-3		0.156	mg	2600	1378
				supplier	Metals	Magnesium (Mg)	7439-95-4		0.069	mg	1150	609
				supplier	Metals	Silver (Ag)	7440-22-4		3.402	mg	56610	29995
External Plating (Sn)	M-011 Other inorganic materials	11.500	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		11.499	mg	999900	101377
				supplier	Matte Sn	Impurities	Proprietary		0.001	mg	100	10